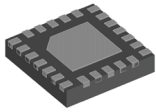
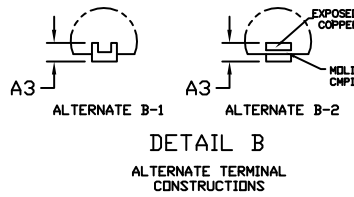
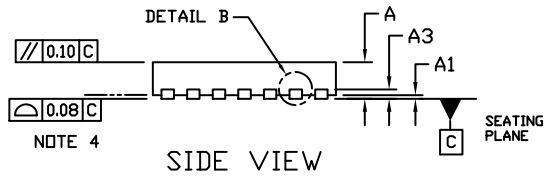
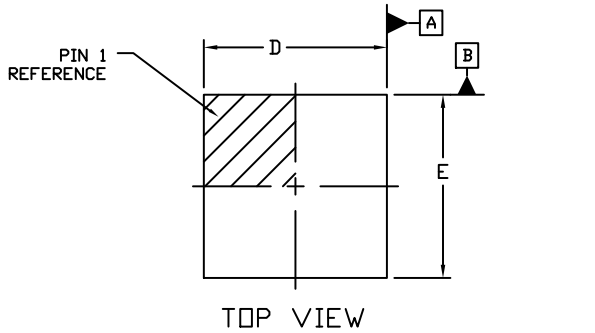


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

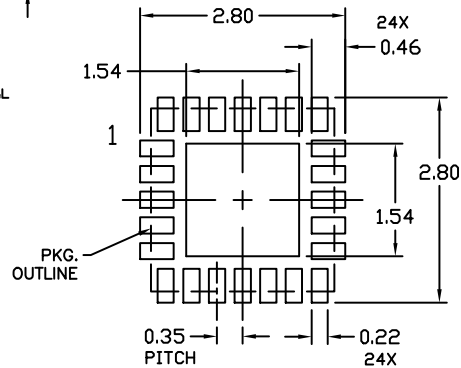
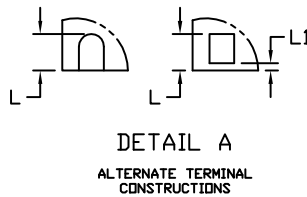
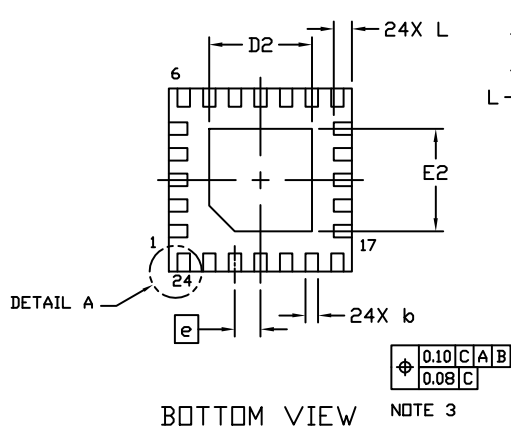


UQFN24 2.5x2.5, 0.35P
CASE 523AB
ISSUE A

DATE 20 AUG 2021



DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.45	0.50	0.55
A1	0.00	---	0.05
A3	0.13 REF		
b	0.12	0.17	0.22
D	2.45	2.50	2.55
D2	1.30	1.40	1.50
E	2.45	2.50	2.55
E2	1.30	1.40	1.50
e	0.35 BSC		
L	0.15	0.25	0.35
L1	0.00	0.05	0.10



GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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